





40V DUAL PNP SMALL SIGNAL TRANSISTOR IN SOT563

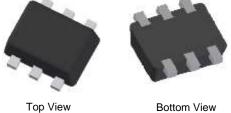
Features

- $BV_{CEO} > -40V$
- I_C = -200mA High Collector Current
- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching
- Ultra-Small Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Finish. Solderable per MIL-STD-202, Method 208 👀
- Weight: 0.003 grams (Approximate)





Top View

Ordering Information (Note 4)

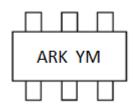
Pı	roduct	Status	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
MMDT	T3906VC-7	Active	AEC-Q101	ARK	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

SOT563



ARK = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: E = 2017) M or \overline{M} = Month (ex: 2 = February)

Date Code Kev

Year	201	7	20	18	2019	2020	2021	2022	202	3 20	24 2	2025	2026	2027
Code	Е		F	-	G	Н	!	J	K	l	_	М	N	0
Month	1	Ja	ın	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code		1		2	3	4	5	6	7	8	9	0	N	D



Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-40	V
Collector-Emitter Voltage	V _{CEO}	-40	V
Emitter-Base Voltage	V_{EBO}	-6	V
Collector Current	Ic	-200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_{D}	150	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	833	°C/W
Operating and Storage and Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 6)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

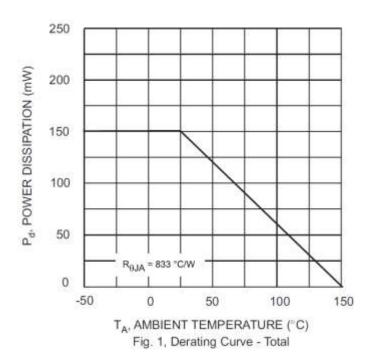
Notes:

^{5.} For the device mounted on minimum recommended pad layout FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

^{6.} Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristic and Derating Information





Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

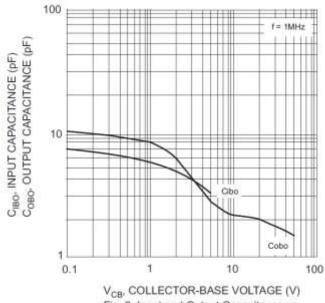
Characteristic	Symbol	Min	Max	Unit	Test Condition		
OFF CHARACTERISTICS							
Collector-Base Breakdown Voltage	BV _{CBO}	-40	_	V	$I_C = -100\mu A, I_E = 0$		
Collector-Emitter Breakdown Voltage	BV_{CEO}	-40		V	$I_C = -1 \text{mA}, I_B = 0$		
Emitter-Base Breakdown Voltage	BV _{EBO}	-6	_	V	$I_E = -100\mu A, I_C = 0$		
Collector Cut-Off Current	I _{CEX}	_	-50	nA	VCE = -30V, VEB(OFF) = -3V		
Base Cut-Off Current	I_{BL}	_	-50	nA	VCE = -30V, VEB(OFF) = -3V		
Emitter- Base Cut-Off Current	I _{EBO}	_	-20	nA	$VEB = -6V, I_C = 0$		
ON CHARACTERISTICS (Note 7)				•			
DC Current Gain	h _{FE}	60 80 100 60 30	 300 	_	$I_{C} = -100\mu A, V_{CE} = -1V$ $I_{C} = -1mA, V_{CE} = -1V$ $I_{C} = -10mA, V_{CE} = -1V$ $I_{C} = -50mA, V_{CE} = -1V$ $I_{C} = -100mA, V_{CE} = -1V$		
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	-0.25 -0.4	V	$I_C = -10\text{mA}$, $I_B = -1\text{mA}$ $I_C = -50\text{mA}$, $I_B = -5\text{mA}$		
Base-Emitter Saturation Voltage	V _{BE(SAT)}	-0.65 —	-0.85 -0.95	V	$I_C = -10\text{mA}$, $I_B = -1\text{mA}$ $I_C = -50\text{mA}$, $I_B = -5\text{mA}$		
SMALL SIGNAL CHARACTERISTICS							
Output Capacitance	Сово	_	4.5	pF	$V_{CB} = -5V$, $f = 1MHz$, $I_E = 0$		
Input Capacitance	C _{IBO}		10	pF	$V_{EB} = -0.5V$, $f = 1MHz$, $I_C = 0$		
Input Impedance	h _{IE}	2	12	kΩ			
Voltage Feedback Ratio	h_{RE}	0.1	10	x 10 ⁻⁴	$V_{CE} = 10V, I_{C} = 1mA,$		
Small Signal Current Gain	h _{FE}	100	400		f = 1kHz		
Output Admittance	hoe	3	60	μS			
Current Gain-Bandwidth Product	f⊤	250		MHz	$V_{CE} = -20V, I_{C} = -10mA,$ f = 100MHz		
Noise Figure	NF	_	4	dB	V_{CE} = -5V, I_C = -100μA, R_S = 1kΩ, f = 1kHz		
SWITCHING CHARACTERISTICS							
Delay Time	t _D	_	35	ns			
Rise Time	t _R		35	ns	$V_{CC} = -3V$, $I_{C} = -10mA$,		
Storage Time		_	200	ns	$-I_{B1} = I_{B2} = -1.0$ mA		
Fall Time	t _F	_	50	ns			

Note:

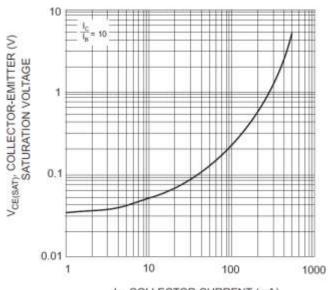
^{7.} Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



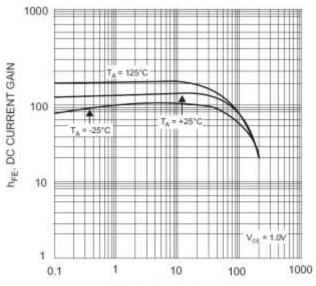
Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)



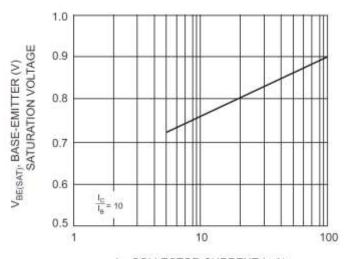
V_{CB}, COLLECTOR-BASE VOLTAGE (V) Fig. 2, Input and Output Capacitance vs. Collector-Base Voltage



I_C, COLLECTOR CURRENT (mA)
Fig. 4, Typical Collector-Emitter Saturation Voltage
vs. Collector Current



I_C, COLLECTOR CURRENT (mA) Fig. 3, Typical DC Current Gain vs Collector Current

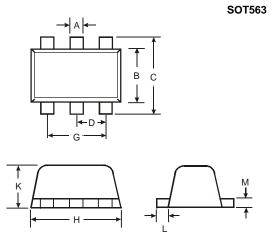


I_C, COLLECTOR CURRENT (mA) Fig. 5, Typical Base-Emitter Saturation Voltage vs. Collector Current



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

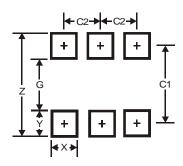


SOT563							
Dim	Min	Max	Тур				
Α	0.15	0.30	0.20				
В	1.10	1.25	1.20				
С	1.55	1.70	1.60				
D	-	-	0.50				
G	0.90	1.10	1.00				
Н	1.50	1.70	1.60				
K	0.55	0.60	0.60				
L	0.10	0.30	0.20				
М	0.10	0.18	0.11				
All	All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT563



Dimensions	SOT563
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2017, Diodes Incorporated

www.diodes.com